

IPC-2152

Standard for Determining Current Carrying Capacity in Printed Board Design

August 2006

A standard developed by IPC

Association Connecting Electronics Industries



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Standard for Determining Current Carrying Capacity in Printed Board Design

Developed by the Current Carrying Capacity Task Group (1-10b) of the Printed Board Design Committee (1-10) of IPC

Users of this standard are encouraged to participate in the development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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| Printed Board Design Committee | Current Carrying Capacity Task Group | Technical Liaisons of the IPC Board of Directors |
|--|---|---|
| Chair Lionel Fullwood WKK Distribution Ltd. | Chair Michael Jouppi Lockheed Martin | Peter Bigelow IMI Inc. |
| Vice Chair Gary Ferrari FTG Circuits | | Sammy Yi Aptina Imaging Corporation |
| Current Carrying Capacity Task Group | | |
| Byron Case, L-3 Communications | Lionel Fullwood, WKK Distribution Ltd. | Michael Miller, NSWC Crane |
| Phillip Chen, L-3 Communications Electronic Systems | Michael Green, Lockheed Martin Space Systems Company | Tim Minner, Coretec Inc. |
| David Corbett, Defense Supply Center Columbus | Christopher Katzko, Shanghai Meadville Electronics Co. Ltd. | Jack Morgan, Ball Aerospace & Technologies |
| William Dieffenbacher, BAE Systems Platform Solutions | Donald Kyle, Schlumberger Well Services | Jack Olson, Caterpillar Inc. |
| C. Don Dupriest, Lockheed Martin Missiles and Fire Control | Jim Long, ITT Power Solutions | William Ortloff, Raytheon Company |
| Gary Ferrari, FTG Circuits | Kenneth Manning, Raytheon Company | Karl Sauter, Sun Microsystems Inc. |
| | | Dewey Whittaker, Honeywell Inc. Air Transport Systems |
| | | John Williams, Raytheon Company |

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| | | |
|--|---------------------------------|----------------------------|
| C. Don Dupriest, Lockheed Martin Missiles and Fire Control | Michael Jouppi, Lockheed Martin | Michael Miller, NSWC Crane |
| Michael Green, Lockheed Martin Space Systems Company | Jack Morgan, Caterpillar Inc. | |

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Standard for Determining Current Carrying Capacity in Printed Board Design

1 SCOPE

This document is intended as a general guide to understanding the relationship between current, conductor size, and temperature, and can be used more specifically in the design and evaluation of copper conductors in printed boards (PBs).

1.1 Purpose The purpose of this document is to provide guidance on determining the appropriate conductor sizes on the finished PB as a function of the current carrying capacity required and the acceptable conductor temperature rise.

1.2 Presentation All dimensions and tolerances in this standard are expressed in hard SI (metric) units and parenthetical soft imperial (inch) units. Users of this standard are expected to use metric dimensions.

1.3 Interpretation “**Shall**,” the imperative form of the verb, is used throughout this standard whenever a requirement is intended to express a provision that is mandatory. Deviation from a “**shall**” requirement may be considered if sufficient data is supplied to justify the exception.

The words “should” and “may” are used whenever it is necessary to express non-mandatory provisions.

“Will” is used to express a declaration of purpose.

To assist the reader, the word “**shall**” is presented in bold characters.

1.4 Definition of Terms The definition of all terms used herein **shall** be in accordance with IPC-T-50 and as defined in 1.4.1 through 1.4.13.

1.4.1 Ambient The surrounding environment coming into contact with the system or component in question.

1.4.2 Base Material The insulating material upon which a conductive pattern may be formed (The base material may be rigid or flexible or both. It may be a dielectric or insulated metal sheet).

1.4.3 Circuitry Layer A layer of PB containing conductors, including ground and voltage planes.

1.4.4 Conductive Pattern The configuration or design of the conductive material on a base material. (This includes conductors, lands, vias, planes, and passive components when these are an integral part of the PB manufacturing process.)

1.4.5 Conductor Spacing The observable distance between adjacent edges (not center-to-center spacing) of isolated conductive patterns in a conductor layer.

1.4.6 Conductor Thickness Thickness of a conductor including additional metallic coatings but excluding non-conductive coatings.

1.4.7 Conductor Width The observable width of a conductor at any point chosen at random on a PB as viewed from directly above unless otherwise specified.

1.4.8 Convection Heat transfer that occurs at the interface of a solid and a fluid or gas that is due to their differences in temperature.

1.4.9 Copper Weight The mass of copper per unit area for a foil, typically expressed in ounces per square foot or grams per square centimeter (these units are not equivalent).

1.4.10 Current-Carrying Capacity The maximum electrical current that can be carried continuously by a conductor, without causing an objectionable degradation of electrical or mechanical properties of the product.